

OSRP0805C1E-0.8T

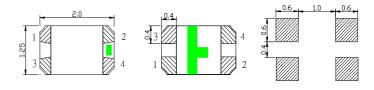
■Features

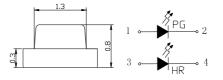
- Bi-Color
- Super high brightness of surface mount LED
- Water Clear Flat Mold
- Compact package outline (LxWxT) of 2.0mm x 1.25mm x 0.8mm
- Compatible to IR reflow soldering.

Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

Outline Dimension





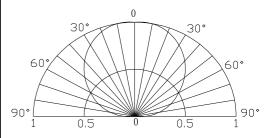
Notes:

- 1. All dimensions are in millimeters ;
- 2. Tolerance is ①.10 mm unless otherwise noted.

■Absolute Maximum Rating

Item	Cumbal	Valu	Unit		
Hem	Symbol	HR	PG	Oilit	
DC Forward Current	I_{F}	20	20	mA	
Pulse Forward Current#	I_{FP}	100	100	mA	
Reverse Voltage	V_R	5	5	V	
Power Dissipation	P_D	46	46	mW	
Operating Temperature	Topr	-40 ~ -	$^{\circ}\! C$		
Storage Temperature	Tstg	-40~ -	$^{\circ}\!\mathbb{C}$		
Lead Soldering Temperature	Tsol	260°C/1	-		

■Directivity



#Pulse width Max 0.1ms, Duty ratio max 1/10

■Electrical -Optical Characteristics

(Ta=25°C)

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				$V_{F}(V)$		$I_R(\mu A)$	Iv(mcd) $\lambda D(nm)$)	2θ1/2(deg)			
	Part Number Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.		
					I _F =5mA		V _R =5V	I _F =5mA							
Ī.	OSRP0805C1E-0.8T	Red	HR		-	1.7	2.3	10	25	45	-	617	625	630	120
		Pure Green	PG		-	2.7	3.3	10	80	120	-	517	525	530	120

^{*1} Tolerance of measurements of dominant wavelength is ± 1 nm







^{*2} Tolerance of measurements of luminous intensity is +15%

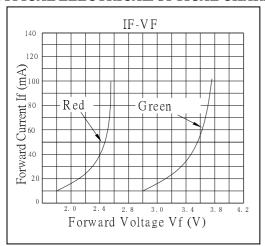
^{*3} Tolerance of measurements of forward voltage is ±0.1V

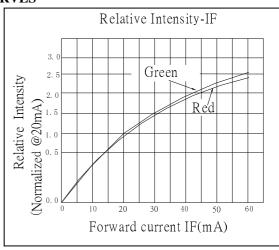


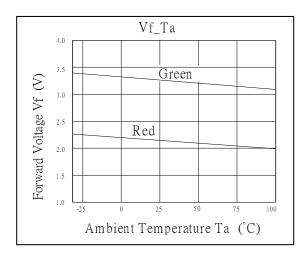
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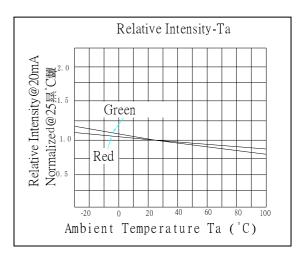
AlGaInP and InGaN LED

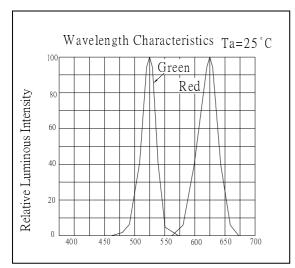
TYPICAL ELECTRICAL/OPTICAL CHARACTERISTIC CURVES



















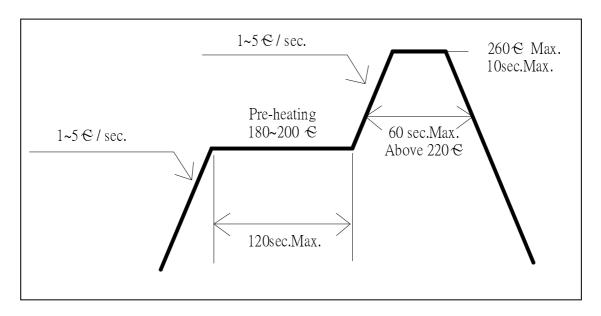


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■ Soldering Conditions

	Reflow Soldering	Hand Soldering			
Pre-Heat	180 ~ 200°C				
Pre-Heat Time	120 sec. Max.				
Peak temperature	260°C Max.	Temperature	350°C Max. 3 sec. Max.		
Dipping Time	10 sec. Max.	Soldering time			
Condition	Refer to Temperature-profile		(one time only)		

• Reflow Soldering Condition(Lead-free Solder)



- *Recommended soldering conditions vary according to the type of LED
- *Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- *A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.





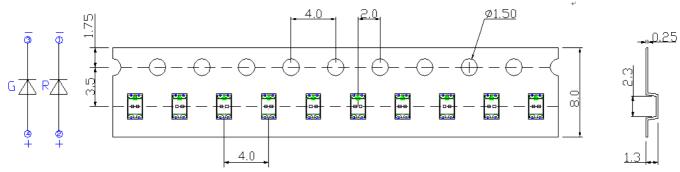




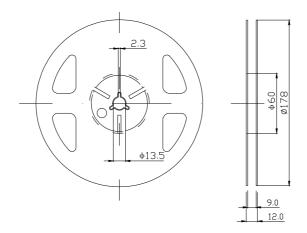


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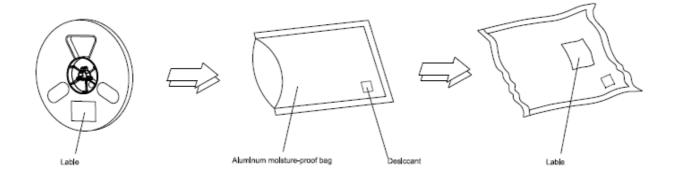
TAPING



Reel Dimensions



■ Moisture Resistant Packaging



Notes:

- 1. Unit: mm
- 2. 3000pcs/Reel











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■ Cautions:

- 1. After open the package, the LED's floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.







